

What is Claims is:

1. A negative-type photosensitive resin composition comprising an epoxy compound and poly(*p*-vinylphenol).
2. The negative-type photosensitive resin composition of claim 1, further comprising a phenol-biphenylene resin.
3. The negative-type photosensitive resin composition of claim 2, wherein the phenol-biphenylene resin is present in the range of 5 – 45 weight % based on the total weight of poly(*p*-vinylphenol) and phenol-biphenylene resin.
4. Method for the formation of a resist pattern, comprising the steps of coating the negative-type photosensitive resin composition of claim 1 on a substrate; exposing the resin composition; and developing of the exposed composition to form the resist pattern.